

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3111781

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOSHIKI YAMAMOTO	08/27/2014
HIDEKI MAKIYAMA	08/27/2014
TAKAAKI TSUNOMURA	09/02/2014
TOSHIAKI IWAMATSU	08/26/2014
RECEIVING PARTY DATA	
Name:	RENESAS ELECTRONICS CORPORATION
Street Address:	1753, SHIMONUMABE, NAKAHARA-KU,
City:	KAWASAKI-SHI, KANAGAWA
State/Country:	JAPAN
Postal Code:	211-8668
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14381562
CORRESPONDENCE DATA	
Fax Number:	(703)610-8686
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(703)903-9000
Email:	sdavis@milesstockbridge.com
Correspondent Name:	MITCHELL W. SHAPIRO
Address Line 1:	MILES & STOCKBRIDGE P.C.
Address Line 2:	1751 PINNACLE DRIVE, SUITE 1500
Address Line 4:	TYSONS CORNER, VIRGINIA 22102-3833
ATTORNEY DOCKET NUMBER:	XA-12712/T3381-20971US01
NAME OF SUBMITTER:	SOPHIA L. DAVIS
SIGNATURE:	/Sophia L. Davis/
DATE SIGNED:	11/18/2014
Total Attachments: 3	
source=Assignment#page1.tif	
source=Assignment#page2.tif	

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Yoshiki Yamamoto (Yoshiki YAMAMOTO)

August 27, 2014

2) Hideki Makiyama (Hideki MAKIYAMA)

August 27, 2014

3) _____ (Takaaki TSUNOMURA)

4) _____ (Toshiaki IWAMATSU)

5) _____

6) _____

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ (Yoshiki YAMAMOTO)	_____
2) _____ (Hideki MAKIYAMA)	_____
3) <u>Takaaki Tsumomura</u> (Takaaki TSUNOMURA)	<u>September 2, 2014</u>
4) _____ (Toshiaki IWAMATSU)	_____
5) _____	_____
6) _____	_____

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Electronics Corporation, a corporation organized under the laws of Japan, located at 1753, Shimonumabe, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8668, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Electronics Corporation, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Electronics Corporation, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Electronics Corporation.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(發明者フルネームサイン)

Date Signed
(署名日)

1) _____ (Yoshiki YAMAMOTO)

2) _____ (Hideki MAKIYAMA)

3) _____ (Takaaki TSUNOMURA)

4) Toshiaki Iwamatsu (Toshiaki IWAMATSU)

5) _____

6) _____

August 26, 2014
